

## 38MHz-320MHz Low Phase Noise VCXO

### FEATURES

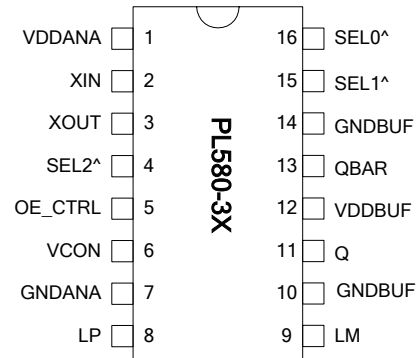
- Less than 0.4ps RMS (12KHz-20MHz) phase jitter for all frequencies.
- Less than 25ps (typ.) peak to peak jitter for all frequencies.
- Low phase noise output (@ 1MHz frequency offset)
  - \* -144dBc/Hz for 155.52MHz
  - \* -140dBc/Hz for 311.04MHz
- 19MHz-40MHz crystal input.
- 38MHz-320MHz output.
- Available in PECL, LVDS, or CMOS outputs.
- No external varicap required.
- Output Enable selector.
- Wide pull range (+/-200ppm).
- 3.3V operation.
- Available in 3x3 QFN or 16-pin TSSOP packages.

### DESCRIPTION

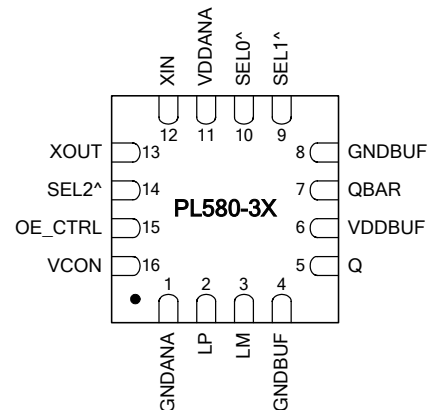
The PL580-3X is a monolithic low jitter and low phase noise VCXO, capable of 0.4ps RMS phase jitter and CMOS, LVDS, or PECL outputs, covering a wide frequency output range up to 320MHz. It allows the control of the output frequency with an input voltage (VCON), using a low cost crystal.

The frequency selector pads of PL580-3X enable output frequencies of  $(2, 4, 8, \text{ or } 16) \times F_{XIN}$ . The PL580-3X is designed to address the demanding requirements of high performance applications such as SONET, GPS, Video, etc.

### PACKAGE PIN ASSIGNMENT



#### 16-pin TSSOP

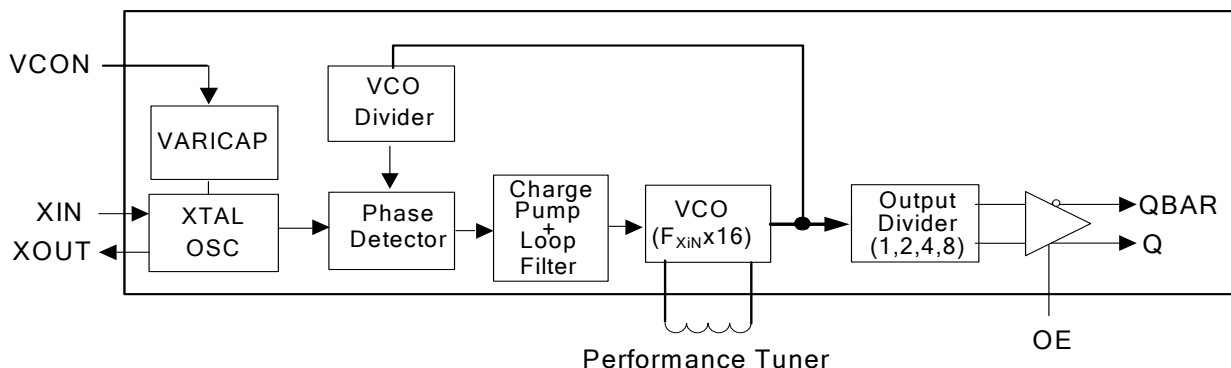


#### 3x3 QFN

Note1: QBAR is used for single ended CMOS output.

Note2: ^ Denotes internal pull up resistor.

### BLOCK DIAGRAM



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### OUTPUT ENABLE LOGICAL LEVELS

Part #	OE	State
PLL580-38 (PECL)	0 (Default)	Output enabled
	1	Tri-state
PLL580-37 & 39 (CMOS or LVDS)	0	Tri-state
	1 (Default)	Output enabled

### PIN DESCRIPTIONS

Name	TSSOP Pin number	3x3mm QFN Pin number	Type	Description
VDDANA	1	11	P	VDD for analog Circuitry.
XIN	2	12	I	Crystal input pin. (See Crystal Specifications on page 4).
XOUT	3	13	O	Crystal output pin. (See Crystal Specifications on page 4).
SEL2	4	14	I	Output frequency Selector pin.
OE_CTRL	5	15	I	Output enable control pin. (See OE_CTRL Logic Levels).
VCON	6	16	I	Voltage control input.
GNDANA	7	1	P	Ground for analog circuitry.
LP	8	2	-	Tuning inductor connection. The inductor is recommended to be a high Q small size 0402 or 0603 SMD component, and must be placed between LP and adjacent LM pin. Place inductor as close to the IC as possible to minimize parasitic effects and to maintain inductor Q.
LM	9	3	-	
GNDBUF	10	4	P	GND connection for output buffer circuitry.
Q	11	5	O	PECL or LVDS output.
VDDBUF	12	6	P	VDD connection for output buffer circuitry. VDDBUF should be separately decoupled from other VDDs whenever possible.
QBAR	13	7	O	Complementary PECL, LVDS, Or single ended CMOS output.
GNDBUF	14	8	P	GND connection for output buffer circuitry.
SEL1	15	9	I	Output frequency Selector pin.
SEL0	16	10	I	Output frequency Selector pin.

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### FREQUENCY SELECTION TABLE

SEL2	SEL1	SEL0	Selected Multiplier/Output Frequency
0	0	0	VCO Max*
0	0	1	VCO Min*
0	1	0	Reserved
0	1	1	Reserved
1	0	0	Fin x 2
1	0	1	Fin x 8
1	1	0	Fin x 16
1	1	1	Fin x 4

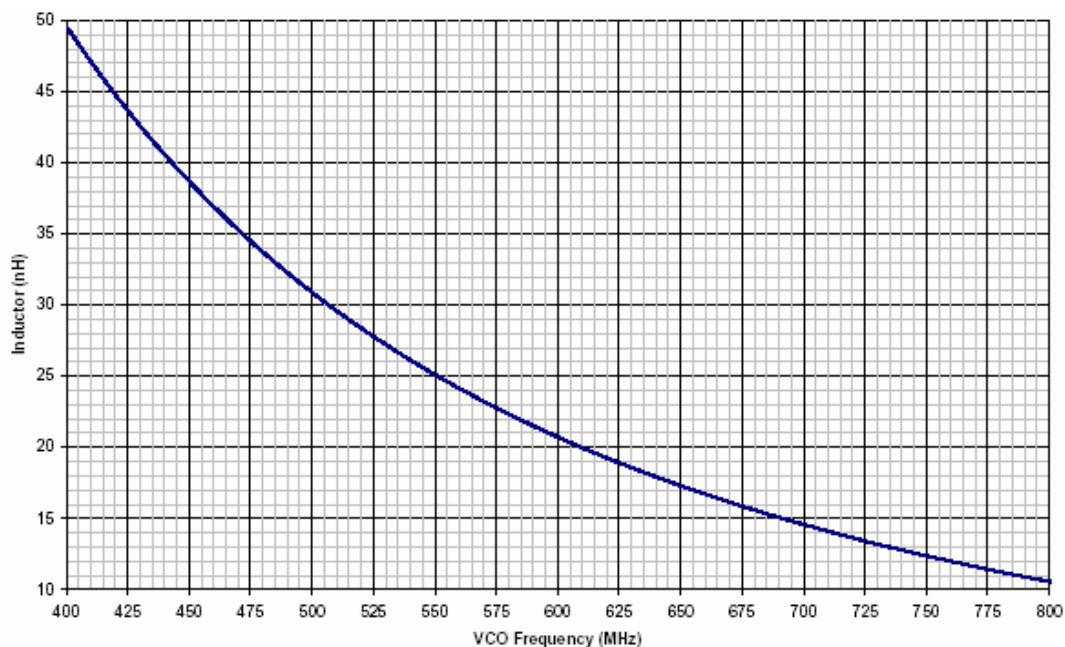
All SEL pads have internal pull-ups (default value is '1'). Bond to GND to set to 0.

\* Special Test Modes to help selecting the inductor value for the target output frequency.

### PERFORMANCE TUNING & INDUCTOR VALUE SELECTION

Please refer to PhaseLink's 'PhasorV Tuning Assistance' software to automatically calculate the optimum inductor values for your application. In addition, the chart below could be used as a reference for quick inductor value selection. Please note that the inductor values mentioned in the table below, or when using 'PhasorV Tuning Assistance' are derived based on the parasitic values of PhaseLink's evaluation board. For performance enhancement of your custom board design, please follow the following instruction:

Use the special test modes "VCO Max" and "VCO Min" to determine the optimum inductor value. "VCO Max" represents the high end of the VCO range and "VCO Min" represents the low end of the VCO range. The output frequency in the "VCO Max" and "VCO Min" test modes is VCO/16. This means that the output frequencies are around the crystal frequency that will be used. The optimum inductor value is where the target crystal frequency is closest to the middle between the "VCO Max" and "VCO Min" output frequencies. In this case the VCO will lock in the middle of its tuning range with maximum margin on either side.



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### ELECTRICAL SPECIFICATIONS

#### 1. Absolute Maximum Ratings

PARAMETERS	SYMBOL	MIN.	MAX.	UNITS
Supply Voltage	$V_{DD}$		4.6	V
Input Voltage, dc	$V_I$	-0.5	$V_{DD}+0.5$	V
Output Voltage, dc	$V_O$	-0.5	$V_{DD}+0.5$	V
Storage Temperature	$T_S$	-65	150	°C
Ambient Operating Temperature*	$T_A$	-40	85	°C
Junction Temperature	$T_J$		125	°C
Lead Temperature (soldering, 10s)			260	°C
ESD Protection, Human Body Model			2	kV

Exposure of the device under conditions beyond the limits specified by Maximum Ratings for extended periods may cause permanent damage to the device and affect product reliability. These conditions represent a stress rating only, and functional operations of the device at these or any other conditions above the operational limits noted in this specification is not implied.

\* **Note:** Operating Temperature is guaranteed by design for all parts (COMMERCIAL and INDUSTRIAL), but tested for COMMERCIAL grade only.

#### 2. Crystal Specifications

PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Crystal Resonator Frequency	$F_{XIN}$	Parallel Fundamental Mode	19		40	MHz
Crystal Loading Rating	$C_L (x_{tal})$	at $V_{CON} = 0V$		17.7		pF
		at $V_{CON} = 1.65V$		9.5		
		at $V_{CON} = 3.3V$		5.4		
Crystal Pullability	$C_0/C_1 (x_{tal})$	AT cut			250	-
Recommended ESR	$R_E$	AT cut			30	$\Omega$

**Note:** Crystal Loading rating: The listed numbers are for the IC only. Specify the crystal for the value at  $V_{CON} = 1.65V$  and add the PCB & package parasitic. A round number (i.e. 12pF) can be achieved by adding external capacitors. Try to add the same value to XIN and XOUT, and please note, that frequency pulling and oscillator gain may decrease.

#### 3. Voltage Control Crystal Oscillator

PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
VCXO Stabilization Time *	$T_{VCXOSTB}$	From power valid			10	ms
VCXO Tuning Range		$F_{XIN} = 19 - 40MHz$ ; $XTAL C_0/C_1 < 250$ $0V \leq V_{CON} \leq 3.3V$		500		ppm
CLK output pullability		$V_{CON}=1.65V, \pm 1.65V$	$\pm 200$			ppm
VCXO Tuning Characteristic				150		ppm/V
Pull range linearity					10	%
VCON pin input impedance			60	80		k $\Omega$
VCON modulation BW		$0V \leq V_{CON} \leq 3.3V, -3dB$	25			kHz

**Note:** Parameters denoted with an asterisk (\*) represent nominal characterization data and are not production tested to any specific limits.

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### 4. General Electrical Specifications

PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Supply Current, Dynamic (with Loaded Outputs)	I <sub>DD</sub>	PECL/LVDS/CMOS	38MHz<F <sub>out</sub> <100MHz		65/45/30	mA
			100MHz<F <sub>out</sub> <320MHz		80/60/40	
Operating Voltage	V <sub>DD</sub>		2.97		3.63	V
Output Clock Duty Cycle		@ 50% V <sub>DD</sub> (CMOS)	45	50	55	%
		@ 1.25V (LVDS)	45	50	55	
		@ V <sub>DD</sub> – 1.3V (PECL)	45	50	55	
Short Circuit Current				±50		mA

**Note:** CMOS operation is not advised above 200MHz with 15pF load; and 320MHz with 10pF load.

### 5. Jitter Specifications

PARAMETERS	CONDITIONS	FREQUENCY	MIN.	TYP.	MAX.	UNITS
Integrated jitter RMS	Integrated 12 kHz to 20 MHz	155.52MHz		0.4	0.5	ps
		311.04MHz		0.4	0.5	
Period jitter RMS	With capacitive decoupling between VDD and GND. Over 10,000 cycles.	77.76MHz		2.5	4	ps
		155.52MHz		3	5	
		311.04MHz		4	7	
Period jitter Peak-to-Peak	With capacitive decoupling between VDD and GND. Over 10,000 cycles.	77.76MHz		18	30	ps
		155.52MHz		20	30	
		311.04MHz		25	35	

### 6. Phase Noise Specifications

PARAMETERS	FREQ.	@10Hz	@100Hz	@1kHz	@10kHz	@100kHz	@1M	@10M	UNITS
Phase Noise relative to carrier (typical)	77.76MHz	-66	-96	-124	-134	-132	-145	-149	dBc/Hz
	155.52MHz	-62	-92	-120	-132	-128	-144	-150	
	311.04MHz	-59	-86	-116	-129	-124	-140	-148	

**Note:** Phase Noise measured at VCON = 0V.

### 7. CMOS Electrical Characteristics

PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Output drive current	I <sub>OH</sub>	V <sub>OH</sub> = V <sub>DD</sub> -0.4V, V <sub>DD</sub> =3.3V	30			mA
	I <sub>OL</sub>	V <sub>OL</sub> = 0.4V, V <sub>DD</sub> = 3.3V	30			mA
Output Clock Rise/Fall Time		0.3V ~ 3.0V with 15 pF load		0.7		ns
Output Clock Rise/Fall Time		20%-80% with 50Ω Load		0.3		ns

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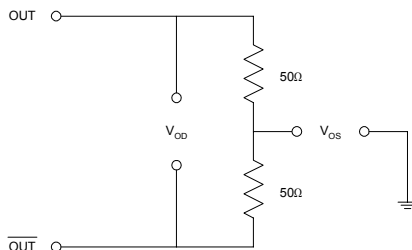
### 8. LVDS Electrical Characteristics

PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Output Differential Voltage	$V_{OD}$	$R_L = 100\ \Omega$ (see figure)	247	355	454	mV
$V_{DD}$ Magnitude Change	$\Delta V_{OD}$		-50		50	mV
Output High Voltage	$V_{OH}$			1.4	1.6	V
Output Low Voltage	$V_{OL}$		0.9	1.1		V
Offset Voltage	$V_{OS}$		1.125	1.2	1.375	V
Offset Magnitude Change	$\Delta V_{OS}$		0	3	25	mV
Power-off Leakage	$I_{OXD}$	$V_{out} = V_{DD}$ or GND $V_{DD} = 0V$		$\pm 1$	$\pm 10$	$\mu A$
Output Short Circuit Current	$I_{OSD}$			-5.7	-8	mA

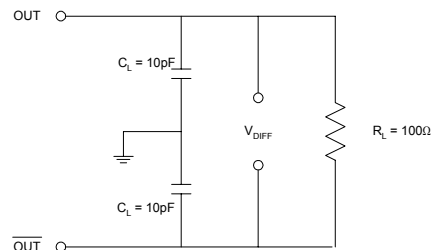
### 9. LVDS Switching Characteristics

PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Differential Clock Rise Time	$t_r$	$R_L = 100\ \Omega$ $C_L = 10\ pF$ (see figure)	0.2	0.7	1.0	ns
Differential Clock Fall Time	$t_f$		0.2	0.7	1.0	ns

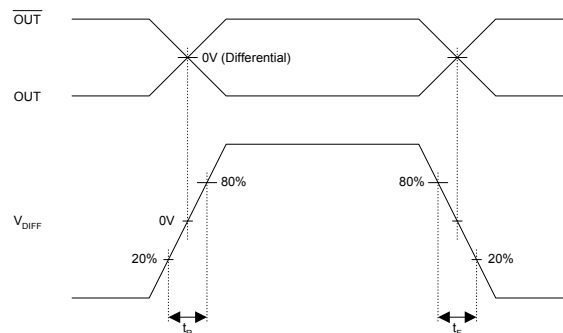
LVDS Levels Test Circuit



LVDS Switching Test Circuit



LVDS Transistion Time Waveform



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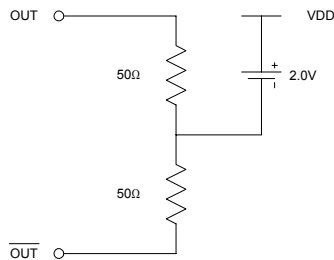
### 10. PECL Electrical Characteristics

PARAMETERS	SYMBOL	CONDITIONS	MIN.	MAX.	UNITS
Output High Voltage	$V_{OH}$	$R_L = 50 \Omega$ to $(V_{DD} - 2V)$ (see figure)	$V_{DD} - 1.025$		V
Output Low Voltage	$V_{OL}$			$V_{DD} - 1.620$	V

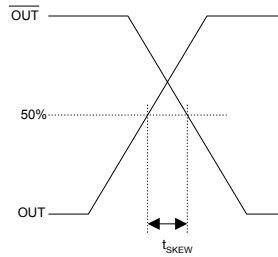
### 11. PECL Switching Characteristics

PARAMETERS	SYMBOL	FREQ.	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Clock Rise & Fall Times	$t_r$ & $t_f$	<150MHz	@20/80% - PECL @80/20% - PECL	0.2	0.5	0.7	ns
Clock Rise & Fall Times		>150MHz <320MHz		0.2	0.4	0.55	

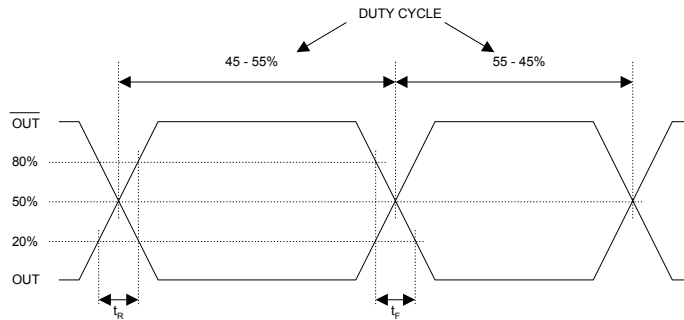
PECL Levels Test Circuit



PECL Output Skew

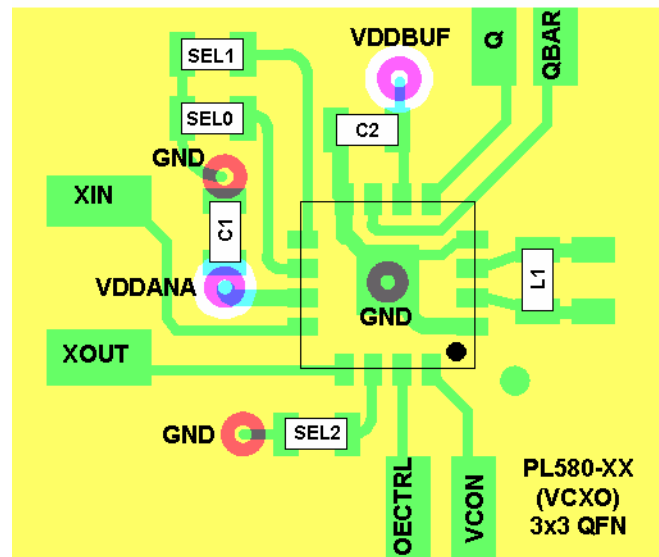
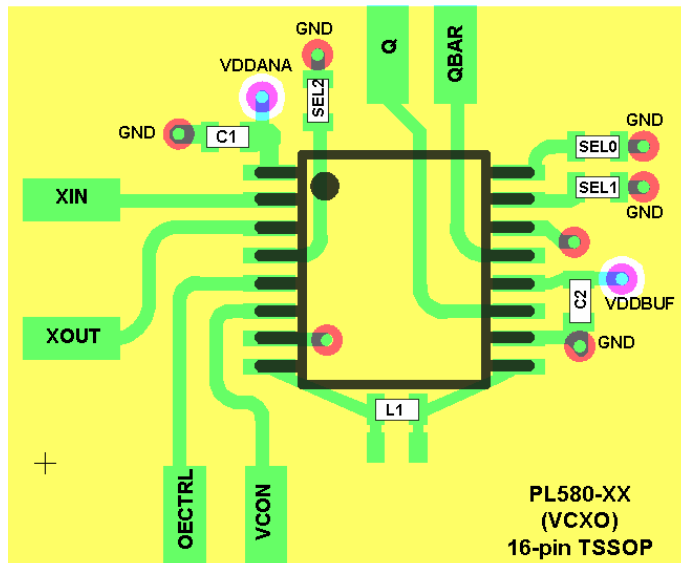


PECL Transition Time Waveform



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### LAYOUT RECOMMENDATIONS



### PCB LAYOUT CONSIDERATIONS FOR PERFORMANCE OPTIMIZATION

The following guidelines are to assist you with a performance optimized PCB design:

- Keep all the PCB traces to PL580 as short as possible, as well as keeping all other traces as far away from it as possible.
- Place the crystal as close as possible to both crystal pins of the device. This will reduce the cross-talk between the crystal and the other signals.
- Separate crystal pin traces from the other signals on the PCB, but allow ample distance between the two crystal pin traces.
- Place a 0.01 $\mu$ F~0.1 $\mu$ F decoupling capacitor between VDD and GND, on the component side of the PCB, close to the VDD pin. It is not recommended to place this component on the backside of the PCB. Going through vias will reduce the signal integrity, causing additional jitter and phase noise.
- It is highly recommended to keep the VDD and GND traces as short as possible.
- When connecting long traces (> 1 inch) to a CMOS output, it is important to design the traces as a transmission line or 'stripline', to avoid reflections or ringing. In this case, the CMOS output needs to be matched to the trace impedance. Usually 'striplines' are designed for 50 $\Omega$  impedance and CMOS outputs usually have lower than 50 $\Omega$  impedance so matching can be achieved by adding a resistor in series with the CMOS output pin to the 'stripline' trace.
- Please contact PhaseLink for the application note on how to design outputs driving long traces or the Gerber files for the PL580 layout.

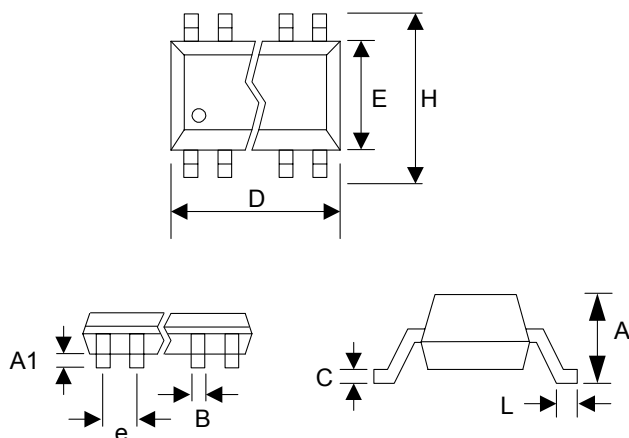


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### PACKAGE INFORMATION

#### 16-PIN SSOP

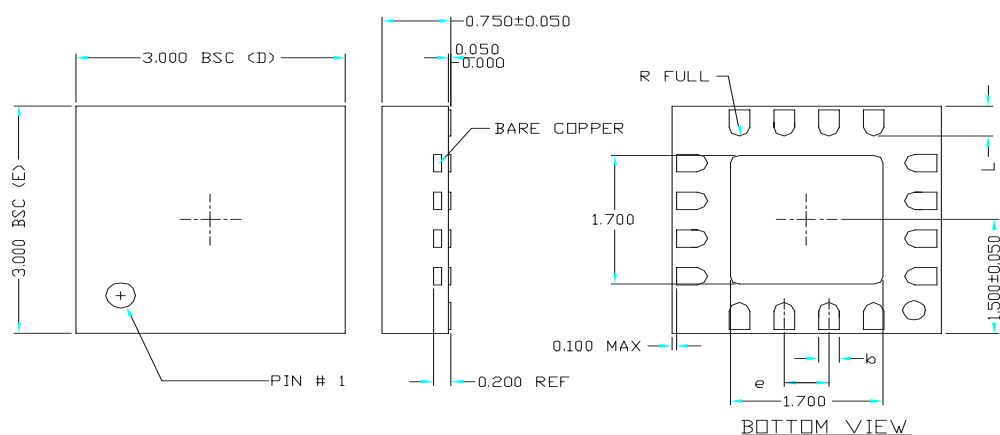
16 PIN TSSOP ( mm )		
Symbol	Min.	Max.
A	-	1.20
A1	0.05	0.15
B	0.19	0.30
C	0.09	0.20
D	4.90	5.10
E	4.30	4.50
H	6.40 BSC	
L	0.45	0.75
e	0.65 BSC	



#### 16-PIN 3x3 QFN

##### VARIATIONS:

SYMBOL	16 LD		
	MIN	NOM	MAX
e	0.50 BSC		
h	0.18	0.23	0.30
L	0.30	0.40	0.50
ND	4		
NE	4		



## 38MHz-320MHz Low Phase Noise VCXO

### ORDERING INFORMATION

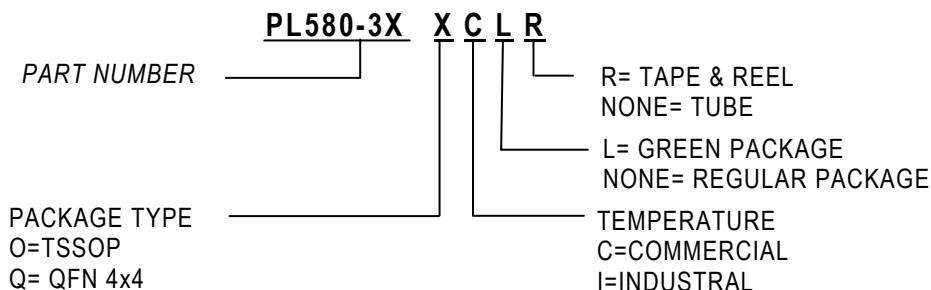
**For part ordering, please contact our Sales Department:**

47745 Fremont Blvd., Fremont, CA 94538, USA

Tel: (510) 492-0990 Fax: (510) 492-0991

#### PART NUMBER

The order number for this device is a combination of the following:  
Device number, Package type and Operating temperature range



Order Number	Marking	Package Option
PL580-37OC	P580-37OC	TSSOP - Tube
PL580-37OC-R	P580-37OC	TSSOP - Tape & Reel
PL580-37OCL	P580-37OCL	TSSOP - Tube (GREEN Package)
PL580-37OCL-R	P580-37OCL	TSSOP - Tape & Reel (GREEN Package)
PL580-37QC	P580-37QC	QFN - Tube
PL580-37QC-R	P580-37QC	QFN - Tape & Reel
PL580-37QCL	P580-37QCL	QFN - Tube (GREEN Package)
PL580-37QCL-R	P580-37QCL	QFN - Tape & Reel (GREEN Package)
PL580-38OC	P580-38OC	TSSOP - Tube
PL580-38OC-R	P580-38OC	TSSOP - Tape & Reel
PL580-38OCL	P580-38OCL	TSSOP - Tube (GREEN Package)
PL580-38OCL-R	P580-38OCL	TSSOP - Tape & Reel (GREEN Package)
PL580-38QC	P580-38QC	QFN - Tube
PL580-38QC-R	P580-38QC	QFN - Tape & Reel
PL580-38QCL	P580-38QCL	QFN - Tube (GREEN Package)
PL580-38QCL-R	P580-38QCL	QFN - Tape & Reel (GREEN Package)
PL580-39OC	P580-39OC	TSSOP - Tube
PL580-39OC-R	P580-39OC	TSSOP - Tape & Reel
PL580-39OCL	P580-39OCL	TSSOP - Tube (GREEN Package)
PL580-39OCL-R	P580-39OCL	TSSOP - Tape & Reel (GREEN Package)
PL580-39QC	P580-39QC	QFN - Tube
PL580-39QC-R	P580-39QC	QFN - Tape & Reel
PL580-39QCL	P580-39QCL	QFN - Tube (GREEN Package)
PL580-39QCL-R	P580-39QCL	QFN - Tape & Reel (GREEN Package)

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